

CDM7-600LR

SURFACE MOUNT SILICON  
N-CHANNEL  
LR POWER MOSFET  
7.0 AMP, 600 VOLT



www.centrasemi.com

ULTRAMOS™



DPAK CASE

**DESCRIPTION:**

The CENTRAL SEMICONDUCTOR CDM7-600LR is a 600 Volt N-Channel MOSFET designed for high voltage, fast switching applications such as Power Factor Correction (PFC), lighting and power inverters. This UltraMOS™ MOSFET combines high voltage capability with ultra low  $r_{DS(ON)}$ , low threshold voltage, and low gate charge for optimal efficiency.

**MARKING: FULL PART NUMBER**

**APPLICATIONS:**

- Power Factor Correction
- Alternative energy inverters
- Solid State Lighting (SSL)

**FEATURES:**

- High voltage capability ( $V_{DS}=600V$ )
- Low gate charge ( $Q_{GS}=3.54nC$  TYP)
- Ultra low  $r_{DS(ON)}$  ( $0.48\Omega$  TYP)

**MAXIMUM RATINGS:** ( $T_C=25^\circ C$  unless otherwise noted)

	SYMBOL		UNITS
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	30	V
Continuous Drain Current (Steady State)	$I_D$	7.0	A
Maximum Pulsed Drain Current, $t_p=10\mu s$	$I_{DM}$	28	A
Continuous Source Current (Body Diode)	$I_S$	7.0	A
Maximum Pulsed Source Current (Body Diode)	$I_{SM}$	28	A
Single Pulse Avalanche Energy (Note 1)	$E_{AS}$	255	mJ
Power Dissipation	$P_D$	60	W
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ C$
Thermal Resistance	$\theta_{JC}$	2.08	$^\circ C/W$
Thermal Resistance	$\theta_{JA}$	110	$^\circ C/W$

Note 1:  $L=79mH, I_{AS}=2.4A, V_{DD}=100V, R_G=25\Omega, \text{Initial } T_J=25^\circ C$

**ELECTRICAL CHARACTERISTICS:** ( $T_C=25^\circ C$  unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
$I_{GSSF}, I_{GSSR}$	$V_{GS}=30V, V_{DS}=0$			100	nA
$I_{DSS}$	$V_{DS}=600V, V_{GS}=0$			1.0	$\mu A$
$BV_{DSS}$	$V_{GS}=0, I_D=250\mu A$	600			V
$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0		4.0	V
$V_{SD}$	$V_{GS}=0, I_S=7.0A$			1.4	V
$r_{DS(ON)}$	$V_{GS}=10V, I_D=3.5A$		0.48	0.58	$\Omega$
$C_{rss}$	$V_{DS}=100V, V_{GS}=0, f=1.0MHz$		6.7		pF
$C_{iss}$	$V_{DS}=100V, V_{GS}=0, f=1.0MHz$		450		pF
$C_{oss}$	$V_{DS}=100V, V_{GS}=0, f=1.0MHz$		29		pF

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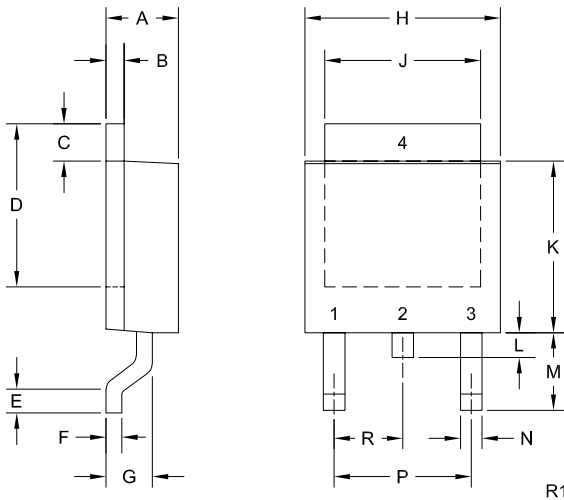


**ELECTRICAL CHARACTERISTICS - Continued:** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

SYMBOL	TEST CONDITIONS	TYP	UNITS
$Q_{g(\text{tot})}$	$V_{DS}=480\text{V}, V_{GS}=10\text{V}, I_D=7.0\text{A}$ (Note 2)	22.9	nC
$Q_{gs}$	$V_{DS}=480\text{V}, V_{GS}=10\text{V}, I_D=7.0\text{A}$ (Note 2)	3.54	nC
$Q_{gd}$	$V_{DS}=480\text{V}, V_{GS}=10\text{V}, I_D=7.0\text{A}$ (Note 2)	13.2	nC
$t_{d(\text{on})}$	$V_{DD}=300\text{V}, V_{GS}=10\text{V}, I_D=7.0\text{A}, R_G=24\Omega$ (Note 2)	10.3	ns
$t_r$	$V_{DD}=300\text{V}, V_{GS}=10\text{V}, I_D=7.0\text{A}, R_G=24\Omega$ (Note 2)	32.6	ns
$t_{d(\text{off})}$	$V_{DD}=300\text{V}, V_{GS}=10\text{V}, I_D=7.0\text{A}, R_G=24\Omega$ (Note 2)	72.2	ns
$t_f$	$V_{DD}=300\text{V}, V_{GS}=10\text{V}, I_D=7.0\text{A}, R_G=24\Omega$ (Note 2)	28.9	ns
$t_{rr}$	$V_{GS}=0, I_S=7.0\text{A}, di/dt=100\text{A}/\mu\text{s}$ (Note 2)	430	ns
$Q_{rr}$	$V_{GS}=0, I_S=7.0\text{A}, di/dt=100\text{A}/\mu\text{s}$ (Note 2)	3.2	$\mu\text{C}$

Note 2: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$

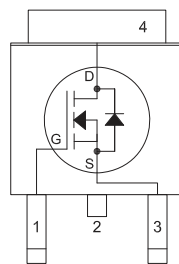
**DPAK CASE - MECHANICAL OUTLINE**



SYMBOL	DIMENSIONS		DIMENSIONS	
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.083	0.108	2.10	2.75
B	0.016	0.032	0.40	0.81
C	0.035	0.063	0.89	1.60
D	0.203	0.228	5.15	5.79
E	0.020	-	0.51	-
F	0.016	0.024	0.40	0.60
G	0.051	0.071	1.30	1.80
H	0.248	0.268	6.30	6.81
J	0.197	0.217	5.00	5.50
K	0.209	0.245	5.30	6.22
L	0.025	0.040	0.64	1.02
M	0.090	0.115	2.30	2.91
N	0.012	0.045	0.30	1.14
P	0.180		4.60	
R	0.090		2.30	

DPAK (REV: R1)

**PIN CONFIGURATION**



**LEAD CODE:**

- 1) Gate
  - 2) Drain
  - 3) Source
  - 4) Drain
- Pin 2 is common to the tab (4)

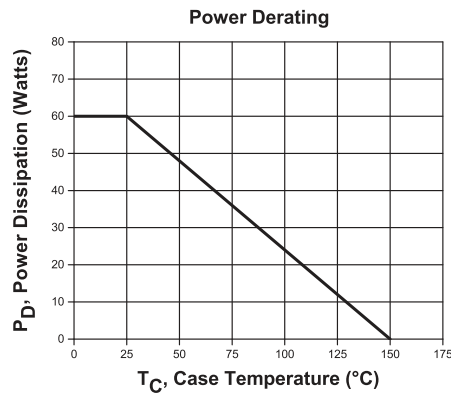
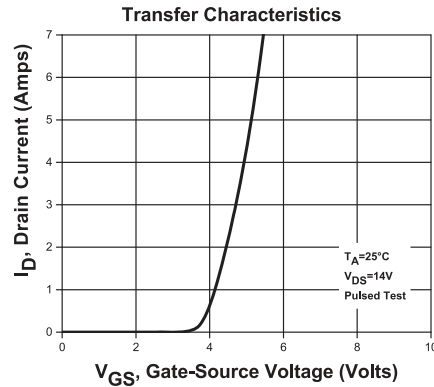
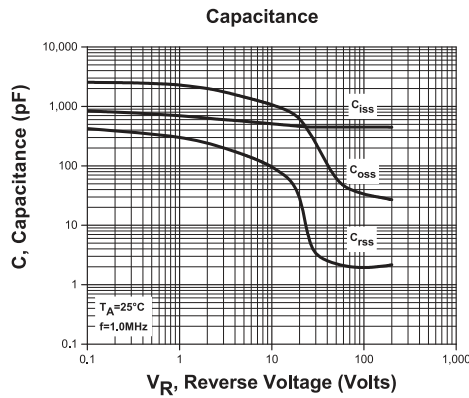
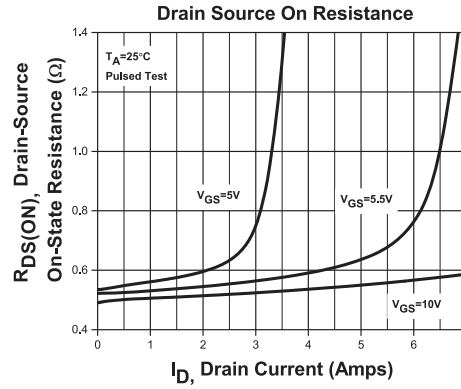
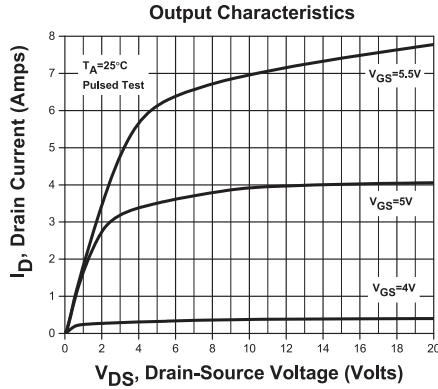
**MARKING: FULL PART NUMBER**

R4 (8-October 2020)

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**TYPICAL ELECTRICAL CHARACTERISTICS**



R3 (21-May 2020)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.  
145 Adams Avenue  
Hauppauge, NY 11788 USA  
Main Tel: (631) 435-1110  
Main Fax: (631) 435-1824  
Support Team Fax: (631) 435-3388  
[www.centrasemi.com](http://www.centrasemi.com)

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